

## **TECHNICAL SPEC FOR Track system**

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**System Model:**

**TEL Clean Track Mk8Z**

**Tool status :**

The tool, inclusive photoresist pumps, and the bypack units have been flushed and cleaned with solvent/DI water, and dry cleaned with CCA. The solvent lines (HMDS, Resist, thinner, developer have been disconnected from the tool), as well as the electric power supply lines. The bypacks of the tool are situated in the basement under the fab. The water cooling line and signal cables are still connected between process unit and bypack. Decommissioning was done by trained Litho technicians.

**Specific Model: MD8271114**

**Wafer size: 6 inch**

**Wafer type: Jeida flat**

**Wafer flow:**

**Number coater/developer modules: 2C/3D**

**InLine system: Yes**

**Resists / Coaters: 4 ( mini)**

**E2 Develop nozzle kits: 3**

**RRC Pumps & kits:**

**Dual-stream nozzles / Developer: NA**

**Solvent & developer auto supply systems: yes**

**Temperature / Humidity controller: Yes**

**Configuration/layout of each block: See below**

GEM: yes

AVG:

HMDS Bubblers: venturi

Power supply: 208 V, 3 Phase, AC Transformer:

Vintage: 1997

<u>Machine</u>	COATER 16
<u>S.N. :</u>	MD8271114
<u>Manufacturing date</u>	16-Apr-97
<u>Machine soft type</u>	Mk 8Z
<u>ARDiMuS</u>	OK
<u>Main Controller</u>	
<u>Process Block1</u>	
<u>Process Block2</u>	
<u>Process Block3</u>	
<u>Process Block 4</u>	
<u>Controller type/model</u>	FC-9821 Ke
<u>Disk</u>	Command Post
<u>Floppy drive</u>	Built-in

Missing parts: none

Defected parts: 1 temperature controller is defective

Operating system:



STG 1-4	○	AD 2-3	AD 2-7		EXT 3-1		AHP 3-8	AHP 3-12	WEE 3-16	WEE 3-17	BU 4-3	
		HP 2-4	HP 2-8	WDS 2-11	DHP 2-12	AHP 3-5	HP 3-9	HP 3-13			BU 4-2	
STG 1-3		HP 2-5	COL 2-9		WDS 2-11	HP 3-6	COL 3-10	COL 3-14			EXT 4-6	
		COL 2-6	COL 2-10		DHP 2-13	COL 3-7	HI-COL 3-11	HI-COL 3-15			COL 4-4	
STG 1-2							MAIN ARM					BU 4-1
STG 1-1			COAT 2-1	COAT 2-2			DEV 3-2	DEV 3-3		DEV 3-4		BU 4-1



		3-1 EXT	3-8 A OVEN	3-12 A OVEN	3-16 WEE 5	3-17 WEE 5	4-2 BUFFER
2-11 WDS	2-12 H OVEN	3-5 A OVEN	3-9 L OVEN	3-13 L OVEN			4-3 BUFFER
		3-6 L OVEN	3-10 T.COOL	3-14 T.COOL			
	2-13 H OVEN	3-7 T.COOL	3-11 T.COOL	3-15 T.COOL			4-6 I Cool
							4-4 I Cool
		3-2 DEV	3-3 DEV	3-4 DEV			4-5 WFSTG7
							4-1 BUFFER

- 1. Config
- 2. Flow
- 3. Lot
- 4. Recipe
- 5. Data
- 6. Status

5-Block No. 6-Unit No. 7-Wafer No.  
888888 8-Unit name

Status (D) Operate (E) Register (F)